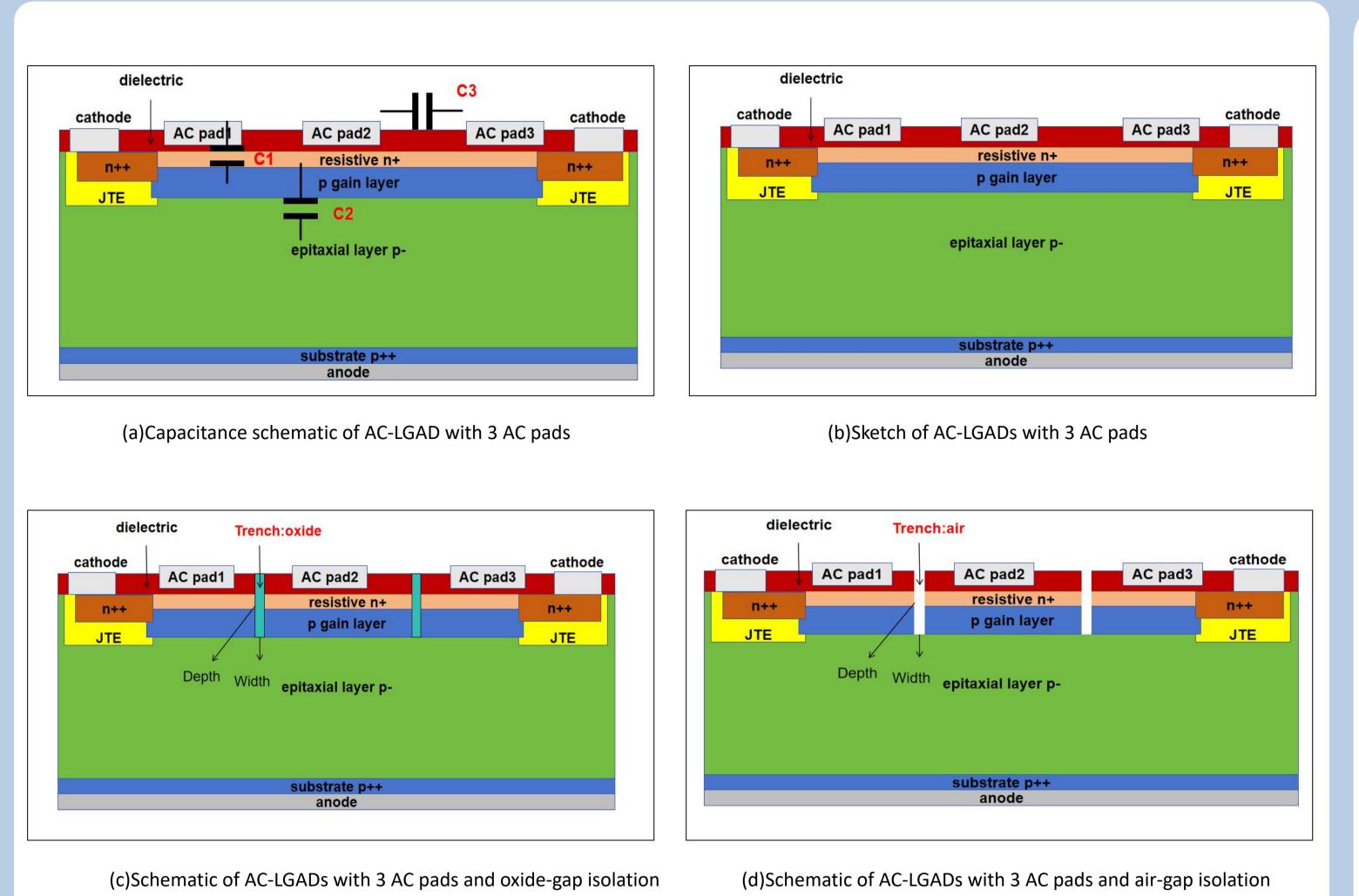
# Capacitance Optimization of AC-LGAD Sensors through Novel Structure Design and TCAD Simulation

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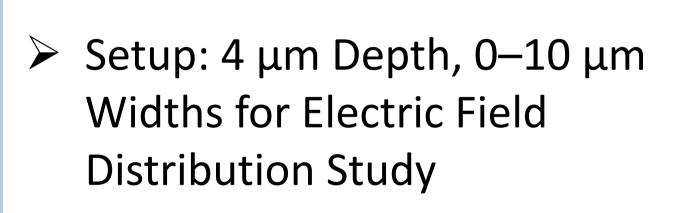


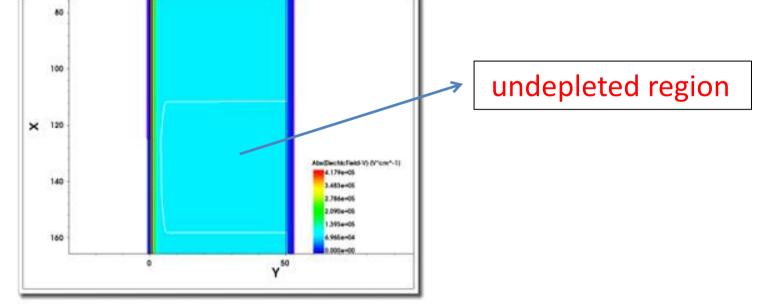
**Fig. 1** Schematic diagrams of AC-LGAD structures: (a) Capacitance schematic (b) traditional structure, (c) with air-gap isolation, and (d) with oxide-gap isolation

## Novel Low-Capacitance AC-LGAD Design: Core Innovations

- Low-k Dielectric Isolation
  - ◆ Method: Add trenches (filled with SiO₂ or air) between resistive electrodes.
  - lacktriangle Effect: Low-k materials cut electric field coupling, reducing  $C_{\rm inter-pad}$  by over 1000x.
  - ◆ Outcome: Minimizes crosstalk, enhances spatial resolution.
- **Optimized Isolation Geometry**
- ◆ Method: Tune isolation structure depth/width via simulations.
- ◆ Effect: Deeper trenches concentrate electric fields; optimized width balances isolation & compactness.
- ◆ Outcome: Ideal capacitance reduction, maintains practical sensor dimensions.

#### Electric Field Distribution Analysis





For the isolation width, both 1 μm and 3 μm are fully depleted

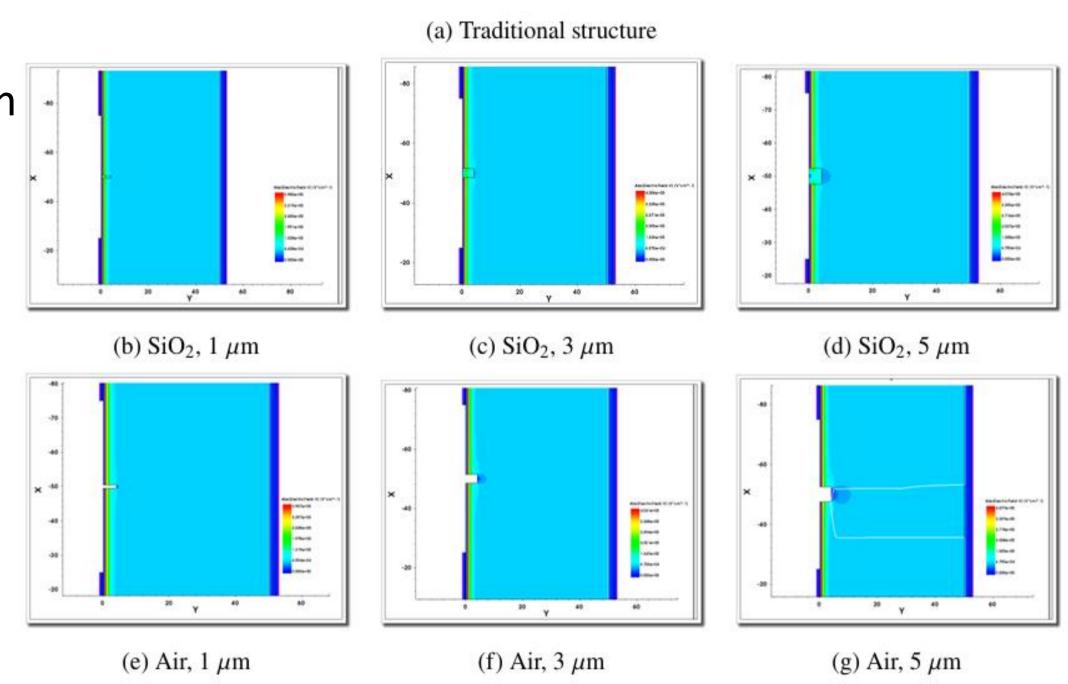


Fig. 4 Electric Field Distributions: Isolation Structures' Effect

#### Summary

This poster presents low-capacitance AC-LGAD structure with low-k dielectric isolation is presented. TCAD simulations show inter-pad capacitance reduction over 1000× and bulk capacitance by ~ 70%. Vacuum isolation outperforms SiO<sub>2</sub> with an additional ~ 30% reduction, effectively suppressing parasitic capacitance and guiding future sensor design.

## Key Parasitic Capacitances in AC-LGAD Sensors

# • C1 (Coupling Capacitance, C coupling)

- $\square$  Location: Metal readout strips  $\overset{\cdot}{\longleftrightarrow}$  semiconductor gain layer (across dielectric)
- ☐ Impact: Weakens signal, slows rise time, distorts waveform
- ☐ Dependence: Dielectric thickness, permittivity, effective area

#### C2 (Bulk Capacitance, C bulk)

- Location: p-n junction (n gain layer ←> p substrate; space charge region as capacitor)
- Impact: Forms low-pass filter (with front-end capacitance) → attenuates high-frequency signals, degrades timing precision
- Dependence: Follows  $C = \frac{\in S}{d}$ ; relies on gain layer/backplane area, separation, medium permittivity

### C3 (Inter-Pad Capacitance, C inter-pad)

- ☐ Location: Adjacent resistive electrodes (via semiconductor bulk, from inter-electrode electric fields)
- ☐ Impact: Causes crosstalk  $\rightarrow$  interferes with position reconstruction, limits spatial resolution
- ☐ Dependence: Electrode spacing, semiconductor permittivity, thickness under electrodes

#### TCAD Simulation of Different Isolation Structure Parameters

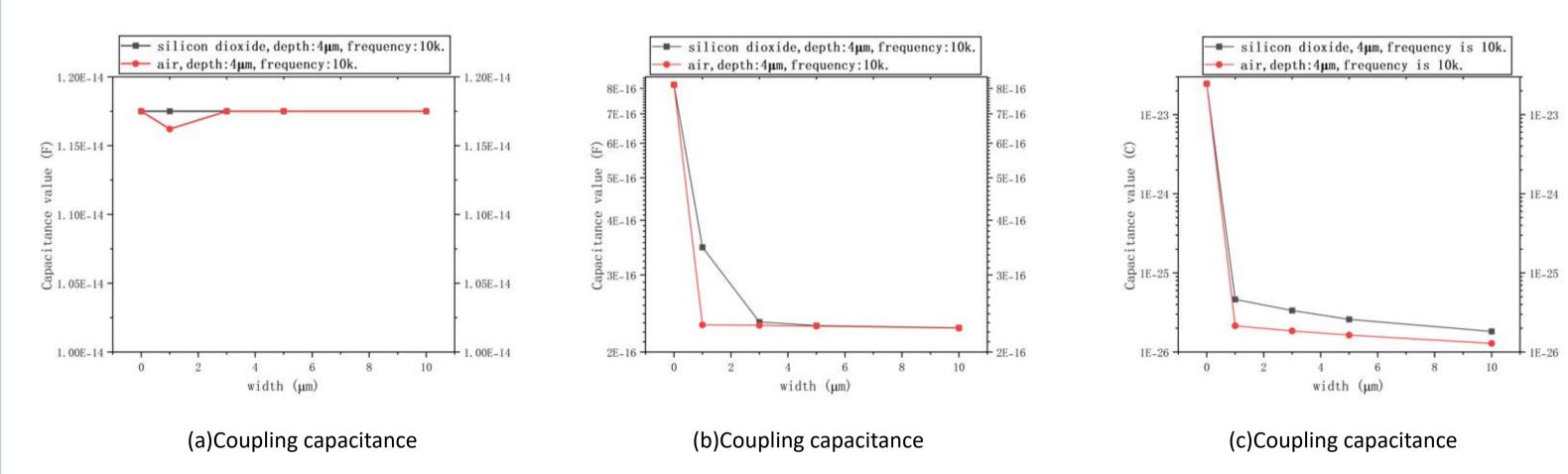


Fig. 2 Effectofdifferentisolationwidthsoncapacitanceparametersatafixeddepthof 4 μm.

- Setup: Fixed isolation depth (4  $\mu$ m), tested isolation widths (0–10  $\mu$ m) to study capacitance changes.
- Key Trends:
  - $C_{\text{inter-pad}}$ : Drops by >3 orders of magnitude (width  $1\rightarrow 10 \mu m$ ), Fig. 2(b).  $C_{\text{bulk}}$ : Decreases by ~70% (width  $1\rightarrow 10 \mu m$ ), Fig. 2(c).
- Reason: Larger width lengthens electrode electric field coupling path, weakens field intensity; per  $C = \frac{\in S}{d}$ , increased d reduces capacitance.
- Minor Impact: Isolation width has little effect on  $\mathcal{C}_{\text{coupling}}$ .

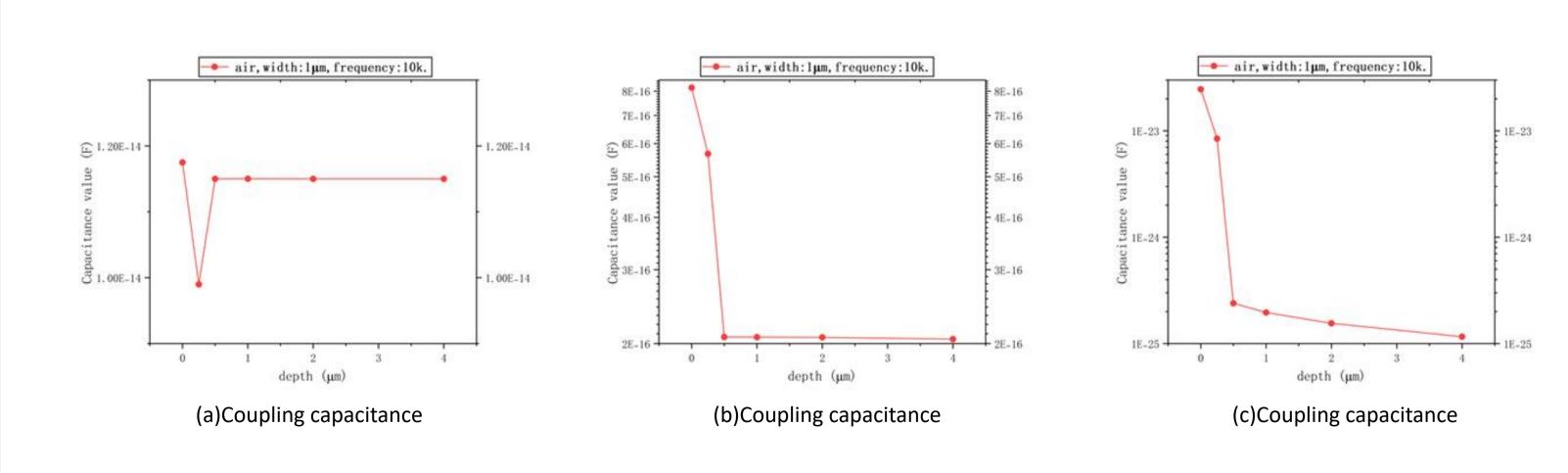


Fig. 3 Isolation Depth vs. Capacitance (Air, 1 μm Width, 10 kHz)

- Setup: Fixed isolation width(1  $\mu$ m), tested isolation depths(0–4  $\mu$ m) to study capacitance changes.
- Observe:

The capacitance reduction at a depth of 0.25  $\mu m$  is far less effective than that at other depths.